

LTM8057 - BGA -38LD 11.25mm X 9mm X 4.92mm (TABLE OF MATERIAL DECLARATION)
The LTM8058 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1069	Barium Compounds	7727-43-7	0.00296	2.77
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1,1156-51-0/9003-36-5/21645-51-2,non-disclosure	0.02202	20.59
				Copper Metal	7440-50-8	0.05704	53.34
				Copper Compounds	147-14-8	0.00003	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.01
				Gold metal or alloy	7440-57-5	0.00015	0.14
				Nickel	7440-02-0	0.00072	0.67
				Zinc	7440-66-6	0.00012	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.01731	16.19
				Acrylic Resin	non-disclosure	0.00565	5.28
				Epoxy Resin	non-disclosure	0.00002	0.02
				Chromium(III) oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00006	0.06
				Talc;not containing fibers like asbertos	14807-96-6	0.00034	0.32
				Aromatic carbonyl Compounds	non-disclosure	0.00032	0.30
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caobonate	471-34-1	0.00000	0.00
				Amine Compounds	non-disclosure	0.00004	0.04
				Leveling agent and others	non-disclosure	0.00013	0.12
2	Solder Paste	Alloy	0.0050	Sn	7440-31-5	0.00471	95.00
				Sb	7440-36-0	0.00025	5.00
3	Passive/Active Components		0.2441	Iron Powder (Fe)	7439-89-6	0.18235	74.70
				Copper (Cu)	7440-50-8	0.04840	19.83
				Nickel (Ni)	7440-02-0	0.00161	0.66
				Tin (Sn)	7440-31-5	0.00181	0.74
				Ceramic (Ba) Compounds	12047-27-7	0.00993	4.07
4	Active Ics	Silicon	0.0040	Silicon	7440-21-3	0.00397	100.00
5	Wire	Gold	0.0002	Au	7440-57-5	0.00019	99.99
6	Solder Ball	SAC305	0.0635	Sn	7440-31-5	0.06128	96.50
				Ag	7440-22-4	0.00191	3.00
				Cu	7440-50-8	0.00032	0.50
7	Encapsulation	Epoxy Resin	0.7047	Fused Silica	60676-86-0	0.54404	77.20
				Epoxy Resin	non-disclosure	0.06272	8.90
				Phenol Resin	non-disclosure	0.06272	8.90
				Crytalline Silica	14808-60-7	0.02114	3.00
				Carbon Black	1333-86-4	0.00352	0.50
				Metal Hydroxide	non-disclosure	0.01057	1.50
Total Package Weight			1.1284				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts